

In re Application of:  
Huang, et al.

Confirmation No.: 1949

Filed: March 16, 1999

**For: In Situ Deposition of a Low K Dielectric Layer, Barrier Layer, Etch Stop Layer and Anti-Reflective Coating for Damascene Application**

Group Art Unit: 2823

**Examiner: George R. Fourson, III**

**MAIL STOP AF**  
**Commissioner for Patents**  
**P.O. Box 1450**  
**Alexandria, VA 22313-1450**

CERTIFICATE OF MAILING  
37 CFR 1.8

I hereby certify that this correspondence is being deposited on  
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10/22/04                      Kurt R. Miller  
Date                                      Signature

Dear Sir:

**RESPONSE TO FINAL OFFICE ACTION DATED AUGUST 25, 2004**

In response to the Final Office Action dated August 25, 2004, having a shortened statutory period for response set to expire on November 25, 2004, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicant believes that no additional fees are due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/2966.X3/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

**The Pending Claims** are reflected in the listing of claims which begins on page 2 of this paper. **Remarks** begin on page 6 of this paper.